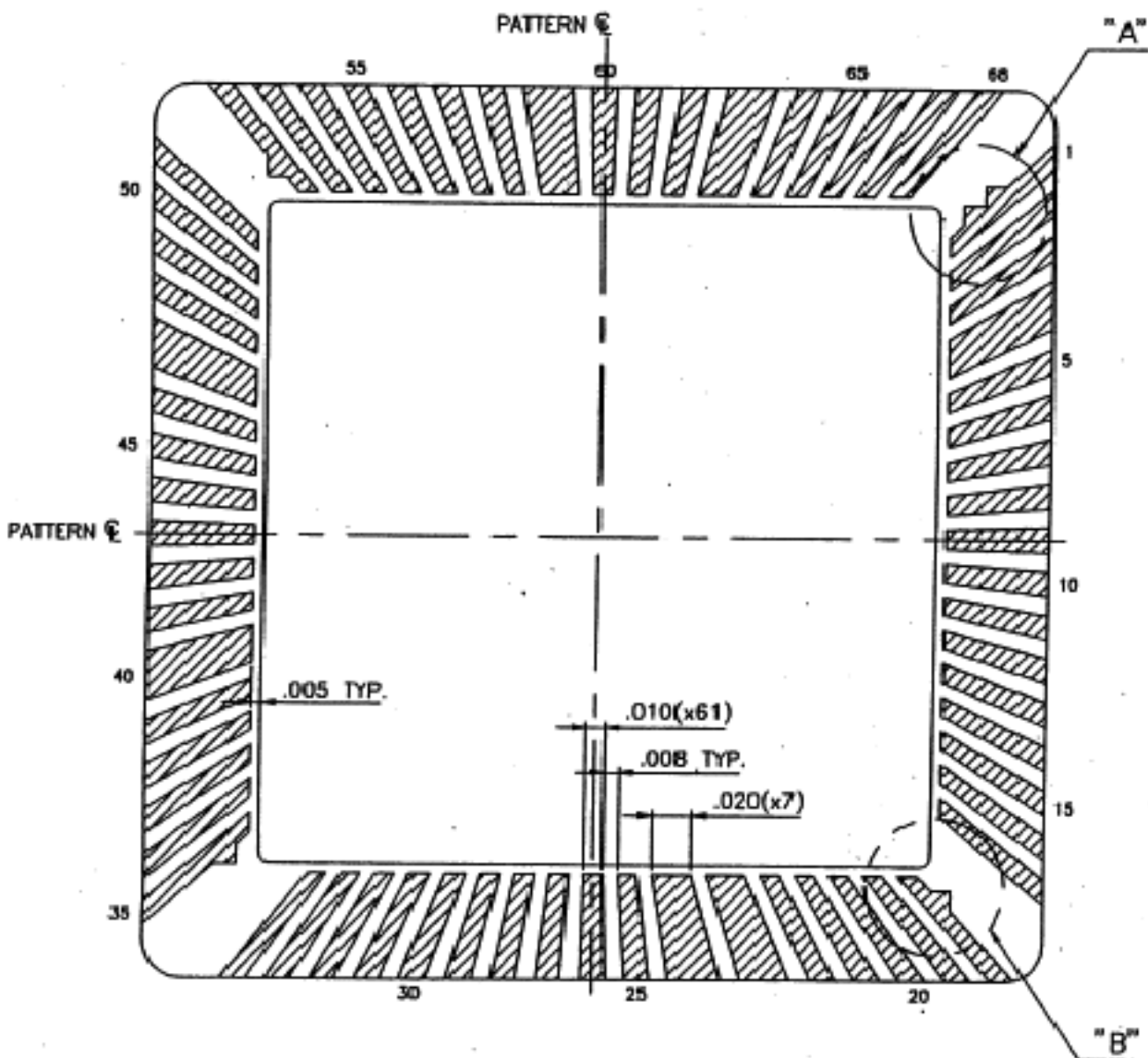
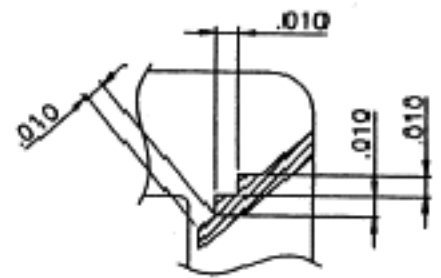


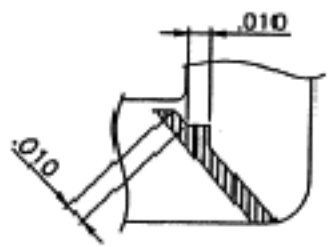
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION
 2. SEAL AREA TO BE METALLIZED
 3. DIE ATTACH AREA TO BE METALLIZED
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : Δ
 V/3 NO. 4,23,24,40,47,59,63 ----- 100mΩ MAX.
 THE OTHERS ----- 500mΩ MAX.



BONDING PATTERN



DETAIL "A"



DETAIL "B"

(W/B NO.1B,35,52)

WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	B2
2	A2
3	B3
4	A3
5	B4
6	A4
7	B5
8	A5
9	B6
10	A6
11	A7
12	B7
13	A8
14	B8
15	A9
16	B9
17	A10
18	B10
19	B11
20	C10

W/B NO.	PIN NO.
21	C11
22	D10
23	D11
24	E11
25	E10
26	F10
27	F11
28	G11
29	G10
30	H11
31	H10
32	J11
33	J10
34	K11
35	K10
36	L10
37	K9
38	L9
39	K8
40	L8

W/B NO.	PIN NO.
41	K7
42	L7
43	K6
44	L6
45	L5
46	K5
47	L4
48	K4
49	L3
50	K3
51	L2
52	K2
53	K1
54	J2
55	J1
56	H2
57	H1
58	G2
59	G1
60	F1

W/B NO.	PIN NO.
61	F2
62	E1
63	E2
64	D1
65	D2
66	C1
67	C2
68	B1
S/R	NC
D/A	NC